

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	91	(via near plug) same (plasma same deposit\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 11:24
L2	20	1 same (etch\$3 same trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 11:17
L3	29	(via near plug) same ((etch\$3 same polymerizat\$3 or deposit\$3) same (cyclic or alternat\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 11:27
S1	63	(via near plug) same polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 11:16
S2	30	S1 same etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/10 20:32
S3	13	S2 same damascene	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/10 20:33
S4	6	((("5501893") or ("6187685") or ("6261962"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 17:00
S5	46	(via adj plug\$3) same (plasma near\$ deposit\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:06
S6	12	S5 and (trench same etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:18
S7	34	S5 not S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:30

S8	2	("6057239").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:36
S9	0	("10/138041").CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:36
S10	1	("0138041").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:36
S11	20	"138041"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 16:37
S12	13	"138041"	US-PGPUB; USPAT	OR	OFF	2005/01/11 16:38
S13	0	"10/138041"	US-PGPUB; USPAT	OR	OFF	2005/01/11 16:38
S14	0	"10138041"	US-PGPUB; USPAT	OR	OFF	2005/01/11 16:38
S15	2	("6794293").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 17:05
S16	10177	((fill\$3 or deposit\$3 or coat\$3) same via) same plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:31
S17	509	S16 same damascene	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 17:42
S18	209	S17 same (trench same etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 17:43
S19	96	((fill\$3 or deposit\$3 or coat\$3) same (via adj plug)) same plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:34

S20	25	S19 same trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:32
S21	9	((fill\$3 or deposit\$3 or coat\$3) same (via adj plug)) same (plasma same spin adj coat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:35
S22	5	(polymer\$3 same (via adj plug)) same (plasma same spin adj coat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:36
S23	2	kang-sean-s.in.	US-PGPUB; USPAT	OR	OFF	2005/01/11 18:38
S24	2	lee-sangheon.in.	US-PGPUB; USPAT	OR	OFF	2005/01/11 18:39
S25	3	chen-wan-lin.in.	US-PGPUB; USPAT	OR	OFF	2005/01/11 18:41
S26	11	((in adj situ) same plug) same fill\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/11 18:41

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	45	(via near3 plug) same ((etch\$3 same polymerizat\$3 or deposit\$3) same (cyclic or alternat\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:52
L2	30	1 and (semiconductor with device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:46
L3	4504	((via or hole or groove) same fill\$3) same ((spin adj coat\$3) same plasma or "cvd")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:58
L4	847	3 same (plug)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:54
L5	26	4 same (trench same etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:57
L6	4467	((via or hole or groove) same fill\$3) same ((spin adj coat\$3) same chemical adj vapor adj deposition or "cvd")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:02
L7	302	6 same (trench same etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:00
L8	4	7 same (via with plug)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:01
L9	70	((via or hole or groove) same fill\$3) same ((spin adj coat\$3) same (chemical adj vapor adj deposition or "cvd"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:12
L10	16	9 and (trench same etching)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:05

L11	63	((via or trench) same fill\$3) same ((spin adj coat\$3) same (chemical adj vapor adj deposition or "cvd"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 14:13
-----	----	--	---	----	-----	------------------